

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231, on the date shown below.

Dated: September 6, 2001

Signature: William Smith

(William Smith)

RECEIVED  
Docket No.: TESSERA 9.0-188 DIV  
(PATENT)  
SEP 14 2001

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Joseph Fjelstad

Application No.: 09/785,104

Filed: February 16, 2001

For: MICROELECTRONIC ELEMENTS WITH  
DEFORMABLE LEADS

Group Art Unit: 2826

Examiner: K. Quinto

Commissioner for Patents  
Washington, DC 20231

AMENDMENT

Dear Sir:

In response to the official action mailed June 6, 2001, applicant submits the following amendments and remarks.

IN THE CLAIMS

CLEAN COPY OF AMENDED CLAIM:

1. A microelectronic element comprising:

(a) a body defining a front surface, said body having pads exposed at said front surface;

(b) flexible leads having pad ends and tip ends, said pad ends of said flexible leads being connected to said pads, said tip ends of at least some of said flexible leads projecting over said front surface of said body, at least some of said flexible leads being spaced apart from said front surface, said tip ends of said flexible leads being independently movable with respect to said body, each of said at least some of said flexible leads being curved in a plane parallel to said front surface of said body.

Please cancel claims 2-7.